Title (en)

Process of manufacturing porous separator for electrochemical power supply

Title (de)

Verfahren zur Herstellung eines porösen Separators für elektrochemische Zelle

Title (fr)

Procédé de fabrication d'un séparateur pour une cellule électrochimique

Publication

EP 0875950 A3 19991215 (EN)

Application

EP 98106356 A 19980407

Priority

US 84709897 A 19970501

Abstract (en)

[origin: EP0875950A2] A method of forming a porous composite separator layer for an electrochemical cell comprising the steps of printing a thin layer of a separator precursor solution on the surface of one of the electrochemical cell electrodes, curing the thin layer of separator precursor solution so that it transforms into a microporous composite separator structure. In the preferred embodiment, the separator precursor solution is formulated as an ink comprising a silica aerogel filler material dispersed in a solution of polymer binder which is dissolved in a suitable solvent. The process allows the manufacture of thin and flexible composite separators which are conformally bonded to the underlying electrodes. <IMAGE>

IPC 1-7

H01M 2/14; H01M 2/16

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

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